

ABSTRACT

When a semiconductor chip is mounted on a mount substrate by bonding bumps, bonding failure is caused by 5 misalignment between the bumps.

Before a semiconductor chip having a plurality of bumps is mounted on a mount substrate (3) having a plurality of bumps (4) by flip chip bonding, a resist layer (5) having a thickness larger than that of the bumps (4) is formed on the 10 mount substrate (3) with the bumps. By patterning the resist layer (5), projecting guides (5A) of semicircular cross section are formed on the mount substrate (3) so as to protrude near the bumps (4) and from a surface on which the bumps (4) are provided, and to have guide faces (curved 15 faces) pointing toward the bumps (4).